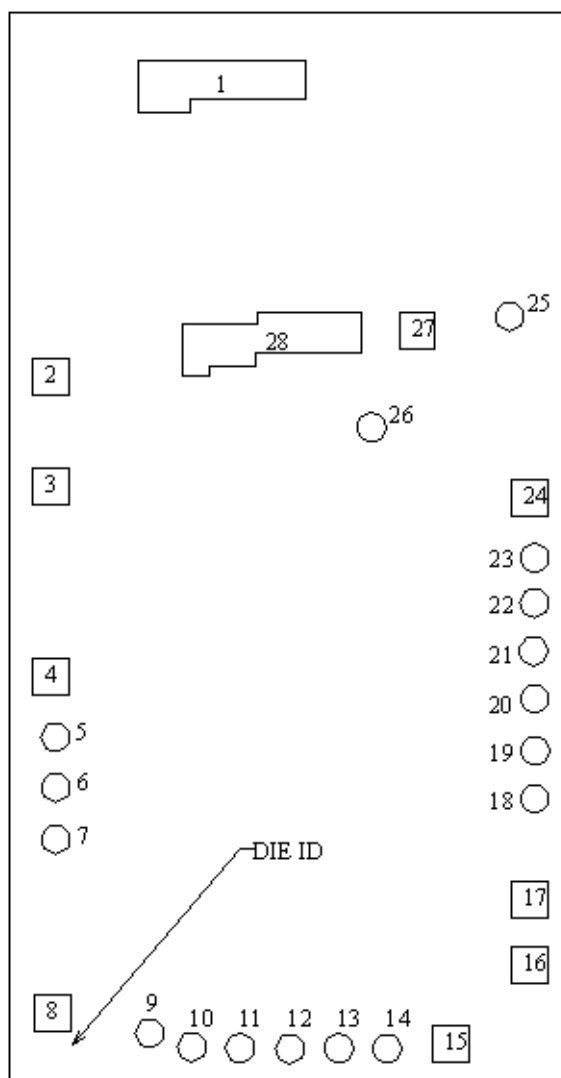


LM2594HV5.0 MDC MWC
SIMPLE SWITCHER® POWER CONVERTER 150 KHZ 0.5A STEP-DOWN VOLTAGE
REGULATOR

June 17, 2002

DIE LAYOUT (C-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1594C	Bond Pad Opening Size (min)	112µm x 112µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1727µm x 3302µm 68mils x 130mils	Back Side Connection	Float Backside
Thickness	406µm Nominal		
Min Pitch	130µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES		PAD SIZE		
		X	Y	X	Y	
OUTPUT	1	-212	1422	512	x	159
NC	2	-737	531	112	x	112
NC	3	-737	195	112	x	112
NC	4	-737	-394	112	x	112
NC	5	-725	-577	88	x	88
NC	6	-723	-733	88	x	88
NC	7	-723	-895	88	x	88
FB	8	-733	-1427	112	x	112
NC	9	-436	-1491	88	x	88
NC	10	-306	-1537	87	x	87
NC	11	-155	-1537	87	x	87
NC	12	-4	-1537	87	x	87
NC	13	147	-1537	87	x	87
NC	14	298	-1537	87	x	87
NC	15	492	-1525	112	x	112
/ON_OFF	16	737	-1283	112	x	112
GND	17	737	-1081	112	x	112
NC	18	750	-771	87	x	87
NC	19	750	-620	87	x	87
NC	20	750	-469	87	x	87
NC	21	750	-318	87	x	87
NC	22	750	-167	87	x	87
NC	23	750	-26	88	x	88
GND	24	737	157	112	x	112
NC	25	672	713	88	x	88
NC	26	247	373	88	x	88
VIN	27	390	675	112	x	112
VIN	28	-58	631	552	x	199

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